Lattice Semiconductor Corporation - M4A5-128/64-10YNC Datasheet

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	128
Number of Gates	-
Number of I/O	64
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-BQFP
Supplier Device Package	100-PQFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-128-64-10ync

GENERAL DESCRIPTION

The ispMACH™ 4A family from Lattice offers an exceptionally flexible architecture and delivers a superior Complex Programmable Logic Device (CPLD) solution of easy-to-use silicon products and software tools. The overall benefits for users are a guaranteed and predictable CPLD solution, faster time-to-market, greater flexibility and lower cost. The ispMACH 4A devices offer densities ranging from 32 to 512 macrocells with 100% utilization and 100% pin-out retention. The ispMACH 4A families offer 5-V (M4A5-xxx) and 3.3-V (M4A3-xxx) operation.

ispMACH 4A products are 5-V or 3.3-V in-system programmable through the JTAG (IEEE Std. 1149.1) interface. JTAG boundary scan testing also allows product testability on automated test equipment for device connectivity.

All ispMACH 4A family members deliver First-Time-Fit and easy system integration with pin-out retention after any design change and refit. For both 3.3-V and 5-V operation, ispMACH 4A products can deliver guaranteed fixed timing as fast as 5.0 ns t_{PD} and 182 MHz f_{CNT} through the SpeedLocking feature when using up to 20 product terms per output (Table 2).

Table 2. ispMACH 4A Speed Grades

Device	Speed Grade							
	-5	-55	-6	-65	-7	-10	-12	-14
M4A3-32 M4A5-32	C				C, I	C, I	I	
M4A3-64/32 M4A5-64/32		C			C, I	C, I	I	
M4A3-64/64		C			C, I	C, I	I	
M4A3-96 M4A5-96		C			C, I	C, I	I	
M4A3-128 M4A5-128		C			C, I	C, I	I	
M4A3-192 M4A5-192			C		C, I	C, I	I	
M4A3-256/128		C		C	C, I	C, I	I	
M4A5-256/128				C	C	C, I	I	
M4A3-256/192 M4A3-256/160					C	C, I	I	
M4A3-384				C		C, I	C, I	I
M4A3-512					C	C, I	C, I	I

Note:

1. *C = Commercial, I = Industrial*

FUNCTIONAL DESCRIPTION

The fundamental architecture of ispMACH 4A devices (Figure 1) consists of multiple, optimized PAL® blocks interconnected by a central switch matrix. The central switch matrix allows communication between PAL blocks and routes inputs to the PAL blocks. Together, the PAL blocks and central switch matrix allow the logic designer to create large designs in a single device instead of having to use multiple devices.

The key to being able to make effective use of these devices lies in the interconnect schemes. In the ispMACH 4A architecture, the macrocells are flexibly coupled to the product terms through the logic allocator, and the I/O pins are flexibly coupled to the macrocells due to the output switch matrix. In addition, more input routing options are provided by the input switch matrix. These resources provide the flexibility needed to fit designs efficiently.

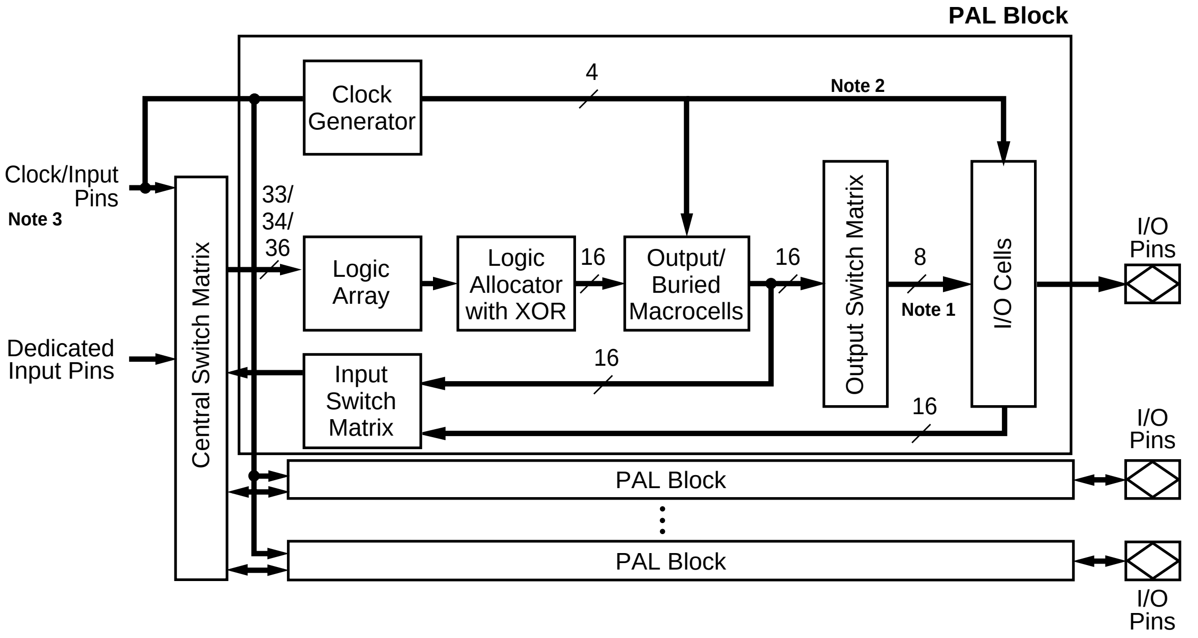

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Figure 1. ispMACH 4A Block Diagram and PAL Block Structure

Notes:

1. *16 for ispMACH 4A devices with 1:1 macrocell-I/O cell ratio (see next page).*
2. *Block clocks do not go to I/O cells in M4A(3,5)-32/32.*
3. *M4A(3,5)-192, M4A(3,5)-256, M4A3-384, and M4A3-512 have dedicated clock pins which cannot be used as inputs and do not connect to the central switch matrix.*

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

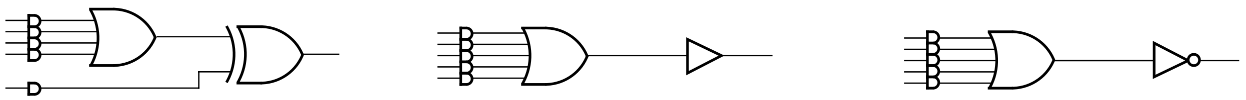
Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in “product term clusters.” The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

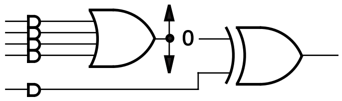
When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.



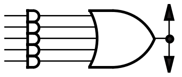
a. Basic cluster with XOR

b. Extended cluster, active high

c. Extended cluster, active low



d. Basic cluster routed away; single-product-term, active high



e. Extended cluster routed away

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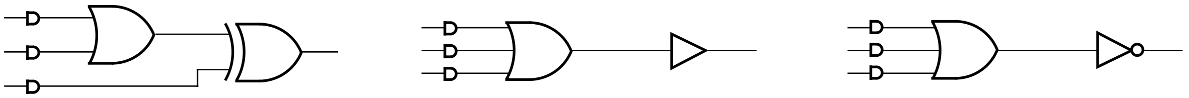
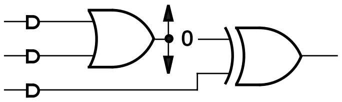
Figure 3. Logic Allocator Configurations: Synchronous Mode



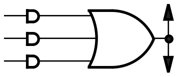
a. Basic cluster with XOR

b. Extended cluster, active high

c. Extended cluster, active low



d. Basic cluster routed away; single-product-term, active high



e. Extended cluster routed away

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Figure 4. Logic Allocator Configurations: Asynchronous Mode

Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE [1]	Q+
D-type Register	D=X	0,1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	$\overline{Q}$
D-type Latch	D=X	1(0)	Q
	D=0	0(1)	0
	D=1	0(1)	1

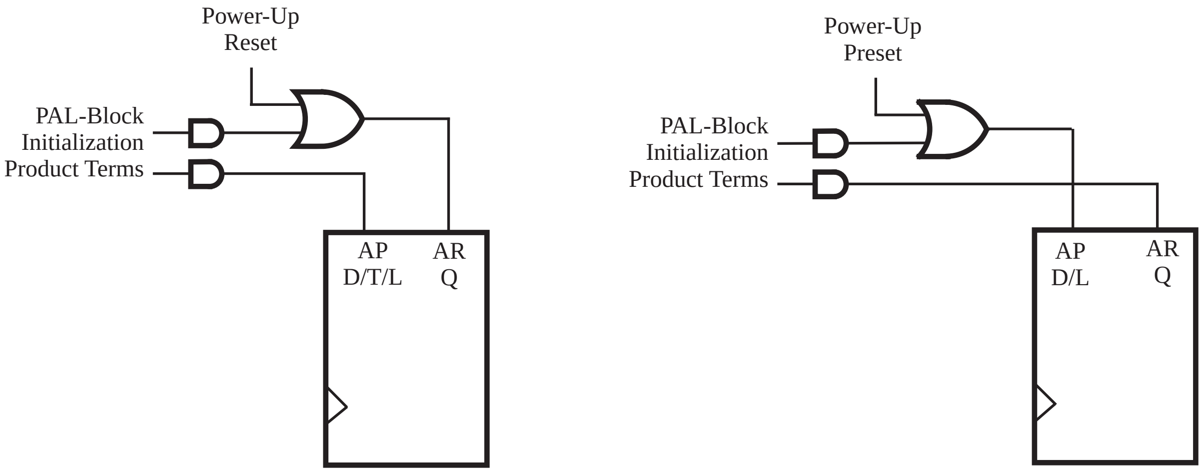
Note:

1. *Polarity of CLK/LE can be programmed*

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset **b. Power-up preset**

17466G-012 17466G-013

Figure 7. Synchronous Mode Initialization Configurations

Table 11. Output Switch Matrix Combinations for M4A3-256/160 and M4A3-256/192

Macrocell	Routable to I/O Cells							
I/O8	M8	M9	M10	M11	M12	M13	M14	M15
I/O9	M8	M9	M10	M11	M12	M13	M14	M15
I/O10	M8	M9	M10	M11	M12	M13	M14	M15
I/O11	M8	M9	M10	M11	M12	M13	M14	M15
I/O12	M8	M9	M10	M11	M12	M13	M14	M15
I/O13	M8	M9	M10	M11	M12	M13	M14	M15
I/O14	M8	M9	M10	M11	M12	M13	M14	M15
I/O15	M8	M9	M10	M11	M12	M13	M14	M15

Table 12. Output Switch Matrix Combinations for M4A(3,5)-32/32

Macrocell	Routable to I/O Cells
M0, M1, M2, M3, M4, M5, M6, M7	I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7
M8, M9, M10, M11, M12, M13, M14, M15	I/O8, I/O9, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15

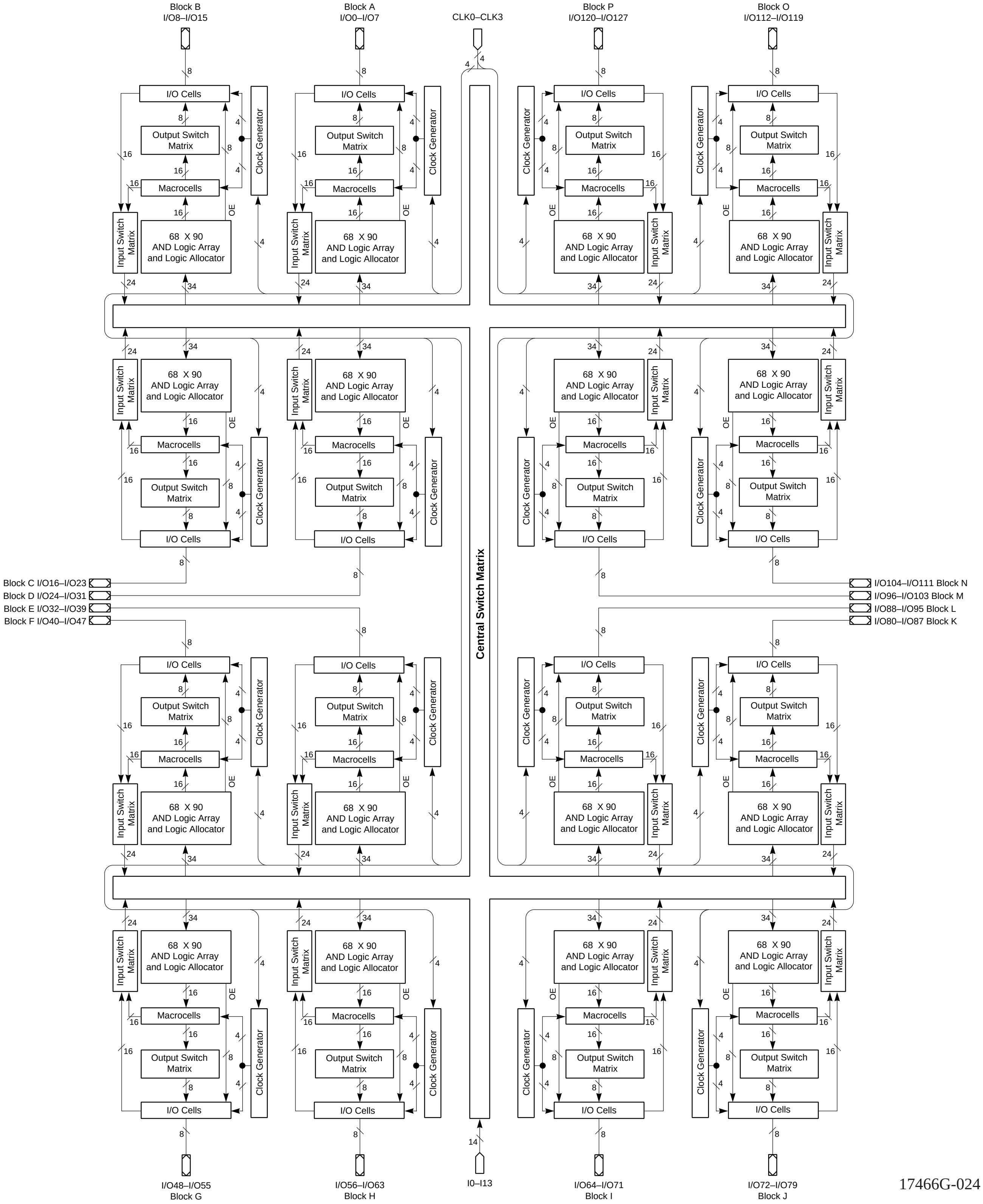
I/O Cell	Available Macrocells
I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7	M0, M1, M2, M3, M4, M5, M6, M7
I/O8, I/O9, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15	M8, M9, M10, M11, M12, M13, M14, M15

Table 13. Output Switch Matrix Combinations for M4A3-64/64

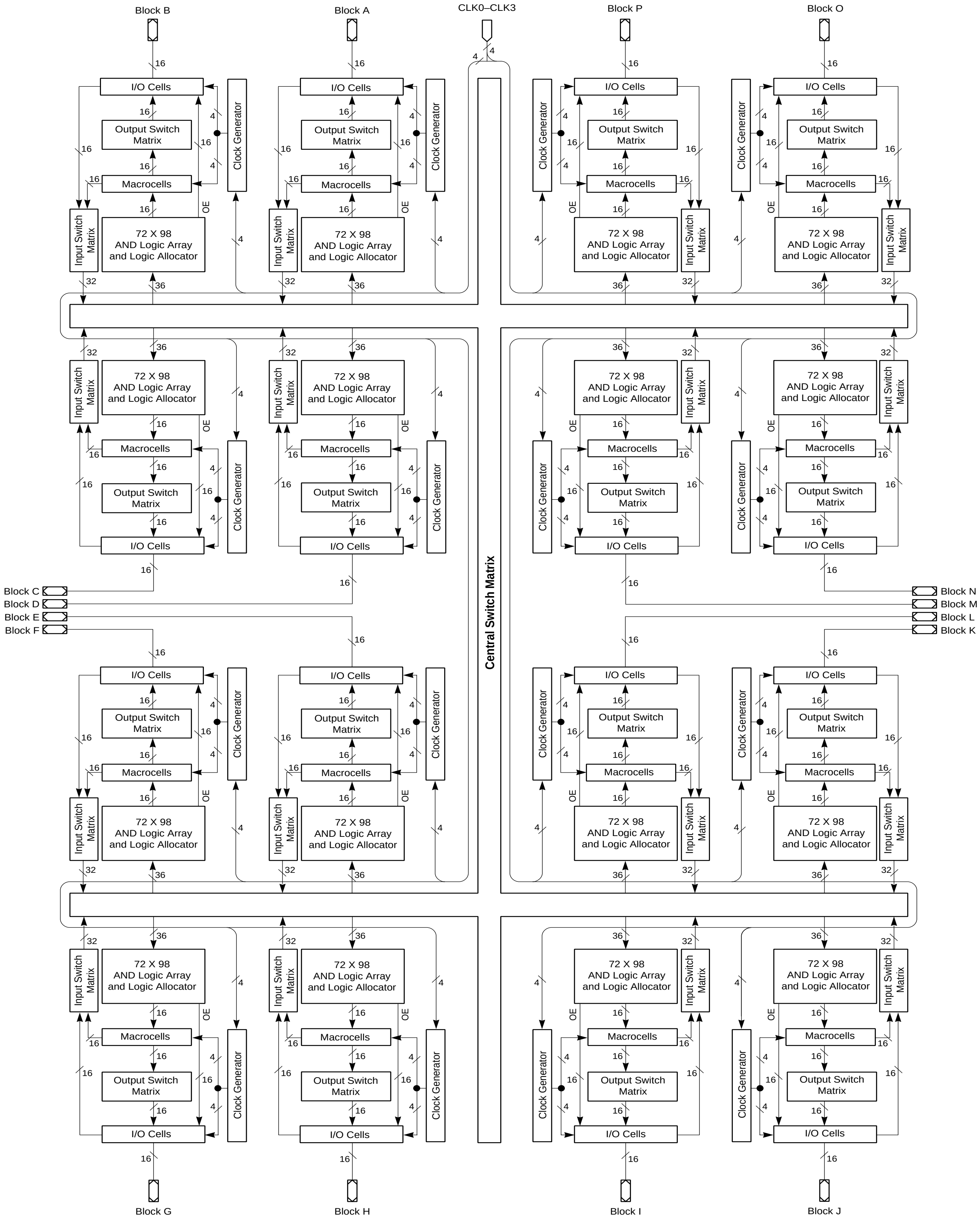
Macrocell	Routable to I/O Cells
MO, M1	I/O0, I/O1, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15
M2, M3	I/O0, I/O1, I/O2, I/O3, I/O12, I/O13, I/O14, I/O15
M4, M5	I/O0, I/O1, I/O2,I/O3, I/O4,I/O5, I/O14, I/O15
M6, M7	I/O0, I/O1, I/O2, I/O3, I/O4, I/O5, I/O6, I/O7
M8, M9	I/O2, I/O3, I/O4, I/O5, I/O6, I/O7, I/O8, I/O9
M10, M11	I/O4, I/O5, I/O6, I/O7, I/O8, I/O9, I/O10, I/O11
M12, M13	I/O6, I/O7, I/O8, I/O9, I/O10, I/O11, I/O12, I/O13
M14, M15	I/O8, I/O9, I/O10, I/O11, I/O12, I/O13, I/O14, I/O15

I/O Cell	Available Macrocells
I/O0, I/O1	M0, M1, M2, M3, M4, M5, M6, M7
I/O2, I/O3	M2, M3, M4, M5, M6, M7, M8, M9
I/O4, I/O5	M4, M5, M6, M7, M8, M9, M10, M11
I/O6, I/O7	M6, M7, M8, M9, M10, M11, M12, M13
I/O8, I/O9	M8, M9, M10, M11, M12, M13, M14, M15
I/O10, I/O11	M0, M1, M10, M11, M12, M13, M14, M15
I/O12, I/O13	M0, M1, M2, M3, M12, M13, M14, M15
I/O14, I/O15	M0, M1, M2, M3, M4, M5, M14, M15

BLOCK DIAGRAM – M4A(3,5)-256/128



BLOCK DIAGRAM – M4A3-256/160, M4A3-256/192



17466G-050

ABSOLUTE MAXIMUM RATINGS

M4A5

Storage Temperature . . . . -65°C to +150°C

Ambient Temperature
with Power Applied. . . . .-55°C to +100°C

Device Junction Temperature. . . . . +130°C

Supply Voltage
with Respect to Ground . . . .-0.5 V to +7.0 V

DC Input Voltage . . . . -0.5 V to V_{CC} + 0.5 V

Static Discharge Voltage . . . . 2000 V

Latchup Current (T_A = -40°C to +85°C) . . . . .200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . . 0°C to +70°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)
Operating in Free Air . . . .-40°C to +85°C

Supply Voltage (V_{CC})
with Respect to Ground. . . . . +4.50 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Conditions	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage	I_{OH} = –3.2 mA, V_{CC} = Min, V_{IN} = V_{IH} or V_{IL}	2.4			V
		I_{OH} = -100 µA, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL}		3.3	3.6	V
V_{OL}	Output LOW Voltage	I_{OL} = 24 mA, V_{CC} = Min, V_{IN} = V_{IH} or V_{IL} (Note 1)			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 2)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 2)			0.8	V
I_{IH}	Input HIGH Leakage Current	V_{IN} = 5.25 V, V_{CC} = Max (Note 3)			10	µA
I_{IL}	Input LOW Leakage Current	V_{IN} = 0 V, V_{CC} = Max (Note 3)			–10	µA
I_{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max, V_{IN} = V_{IH} or V_{IL} (Note 3)			10	µA
I_{OZL}	Off-State Output Leakage Current LOW	V_{OUT} = 0 V, V_{CC} = Max , V_{IN} = V_{IH} or V_{IL} (Note 3)			–10	µA
I_{SC}	Output Short-Circuit Current	V_{OUT} = 0.5 V, V_{CC} = Max (Note 4)	–30		–160	mA

Notes:

1. *Total I_{OL} for one PAL block should not exceed 64 mA.*
2. *These are absolute values with respect to device ground, and all overshoots due to system or tester noise are included.*
3. *I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).*
4. *Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. V_{OUT} = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.*

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES[1]

		-5		-55		-6		-65		-7		-10		-12		-14		Unit
		Min	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
Combinatorial Delay:																		
t_{PDi}	Internal combinatorial propagation delay		3.5		4.0		4.3		4.5		5.0		7.0		9.0		11.0	ns
t_{PD}	Combinatorial propagation delay		5.0		5.5		6.0		6.5		7.5		10.0		12.0		14.0	ns
Registered Delays:																		
t_{SS}	Synchronous clock setup time, D-type register	3.0		3.5		3.5		3.5		5.0		5.5		7.0		10.0		ns
t_{SST}	Synchronous clock setup time, T-type register	4.0		4.0		4.0		4.0		6.0		6.5		8.0		11.0		ns
t_{SA}	Asynchronous clock setup time, D-type register	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t_{SAT}	Asynchronous clock setup time, T-type register	3.0		3.0		3.0		3.5		4.5		5.0		6.0		9.0		ns
t_{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t_{HA}	Asynchronous clock hold time	2.5		2.5		2.5		3.0		3.5		4.0		5.0		8.0		ns
t_{COSi}	Synchronous clock to internal output		2.5		2.5		2.8		3.0		3.0		3.0		3.5		3.5	ns
t_{COS}	Synchronous clock to output		4.0		4.0		4.5		5.0		5.5		6.0		6.5		6.5	ns
t_{COAi}	Asynchronous clock to internal output		5.0		5.0		5.0		5.0		6.0		8.0		10.0		12.0	ns
t_{COA}	Asynchronous clock to output		6.5		6.5		6.8		7.0		8.5		11.0		13.0		15.0	ns
Latched Delays:																		
t_{SSL}	Synchronous latch setup time	4.0		4.0		4.0		4.5		6.0		7.0		8.0		10.0		ns
t_{SAL}	Asynchronous latch setup time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t_{HSL}	Synchronous latch hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t_{HAL}	Asynchronous latch hold time	3.0		3.0		3.5		3.5		4.0		4.0		5.0		8.0		ns
t_{PDLi}	Transparent latch to internal output		5.5		5.5		5.8		6.0		7.5		9.0		11.0		12.0	ns
t_{PDL}	Propagation delay through transparent latch to output		7.0		7.0		7.5		8.0		10.0		12.0		14.0		15.0	ns
t_{GOSi}	Synchronous gate to internal output		3.0		3.0		3.0		3.0		3.5		4.5		7.0		8.0	ns
t_{GOS}	Synchronous gate to output		4.5		4.5		4.8		5.0		6.0		7.5		10.0		11.0	ns
t_{GOAi}	Asynchronous gate to internal output		6.0		6.0		6.0		6.0		8.5		10.0		13.0		15.0	ns
t_{GOA}	Asynchronous gate to output		7.5		7.5		7.8		8.0		11.0		13.0		16.0		18.0	ns
Input Register Delays:																		
t_{SIRS}	Input register setup time	1.5		1.5		2.0		2.0		2.0		2.0		2.0		2.0		ns
t_{HIRS}	Input register hold time	2.5		2.5		3.0		3.0		3.0		3.0		3.0		4.0		ns
t_{ICOSi}	Input register clock to internal feedback		3.0		3.0		3.0		3.0		3.5		4.5		6.0		6.0	ns
Input Latch Delays:																		
t_{SIL}	Input latch setup time	1.5		1.5		1.5		2.0		2.0		2.0		2.0		2.0		ns
t_{HIL}	Input latch hold time	2.5		2.5		2.5		3.0		3.0		3.0		3.0		4.0		ns
t_{IGOSi}	Input latch gate to internal feedback		3.5		3.5		3.8		4.0		4.0		4.0		4.0		5.0	ns
t_{PDILi}	Transparent input latch to internal feedback		1.5		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns

ispMACH 4A TIMING PARAMETERS OVER OPERATING RANGES[1]

		-5		-55		-6		-65		-7		-10		-12		-14		
		Min	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**
Frequency:																		
f_{MAXS}	External feedback, D-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	143		133		125		118		95.2		87.0		74.1		60.6		MHz
	External feedback, T-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SST} + t_{COS})$	125		125		118		111		87.0		80.0		69.0		57.1		MHz
	Internal feedback (f_{CNT}), D-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COSi})$	182		167		160		154		125		118		95.0		74.1		MHz
	Internal feedback (f_{CNT}), T-type, Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SST} + t_{COSi})$	154		154		148		143		111		105		87.0		69.0		MHz
	No feedback[2], Min of $1/(t_{WLS} + t_{WHS})$, $1/(t_{SS} + t_{HS})$ or $1/(t_{SST} + t_{HS})$	250		250		200		200		154		125		100		83.3		MHz
f_{MAXA}	External feedback, D-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	111		111		108		100		83.3		66.7		55.6		43.5		MHz
	External feedback, T-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SAT} + t_{COA})$	105		105		102		95.2		76.9		62.5		52.6		41.7		MHz
	Internal feedback (f_{CNTA}), D-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COAi})$	133		133		125		125		105		83.3		66.7		50.0		MHz
	Internal feedback (f_{CNTA}), T-type, Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SAT} + t_{COAi})$	125		125		125		118		95.2		76.9		62.5		47.6		MHz
	No feedback[2], Min of $1/(t_{WLA} + t_{WHA})$, $1/(t_{SA} + t_{HA})$ or $1/(t_{SAT} + t_{HA})$	167		167		143		143		125		100		62.5		55.6		MHz
f_{MAXI}	Maximum input register frequency, Min of $1/(t_{WIRH} + t_{WIRL})$ or $1/(t_{SIRS} + t_{HIRS})$	167		167		143		143		125		100		83.3		83.3		MHz

Notes:

1. *See "Switching Test Circuit" document on the Literature Download page of the Lattice web site.*
2. *This parameter does not apply to flip-flops in the emulated mode since the feedback path is required for emulation.*

CAPACITANCE [1]

Parameter Symbol	Parameter Description	Test Conditions		Typ	Unit
C_{IN}	Input capacitance	V_{IN}=2.0 V	3.3 V or 5 V, 25°C, 1 MHz	6	pF
$C_{I/O}$	Output capacitance	V_{OUT}=2.0V	3.3 V or 5 V, 25°C, 1 MHz	8	pF

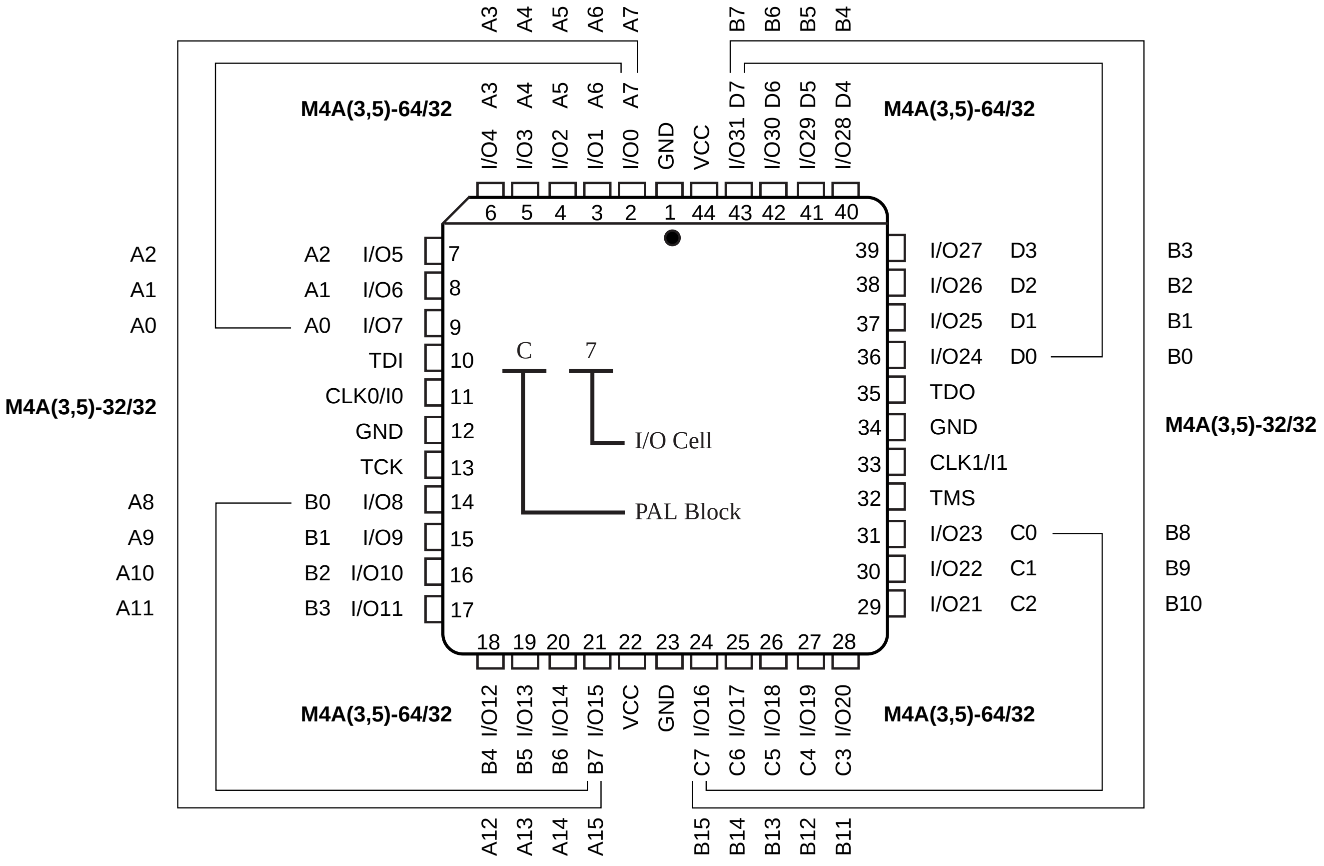
Note:

1. *These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where this parameter may be affected.*

44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

44-Pin PLCC



17466G-026

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

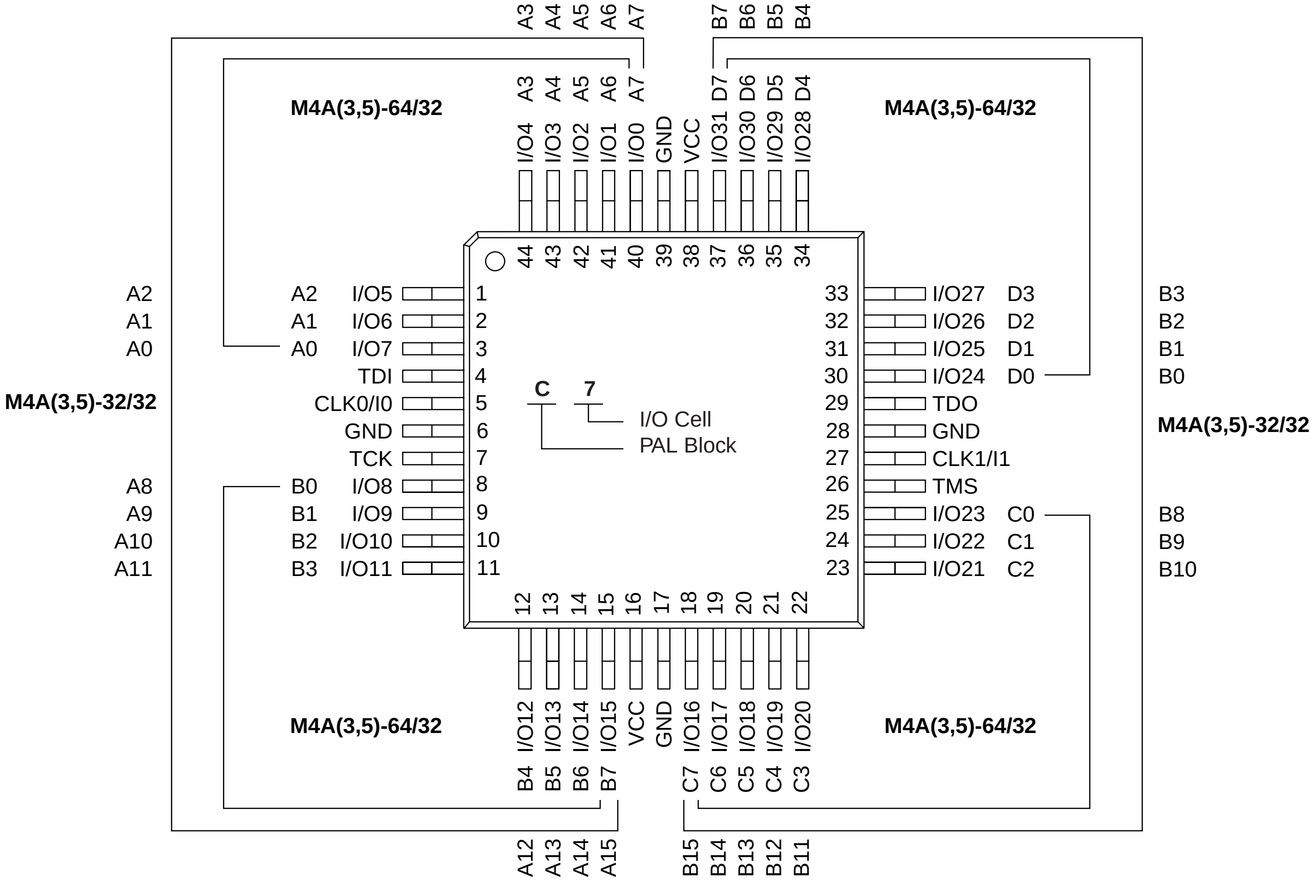
TMS = Test Mode Select

TDO = Test Data Out

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

44-Pin TQFP (1.0mm Thickness)



PIN DESIGNATIONS

CLK / I = Clock or Input

GND = Ground

I / O = Input / Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

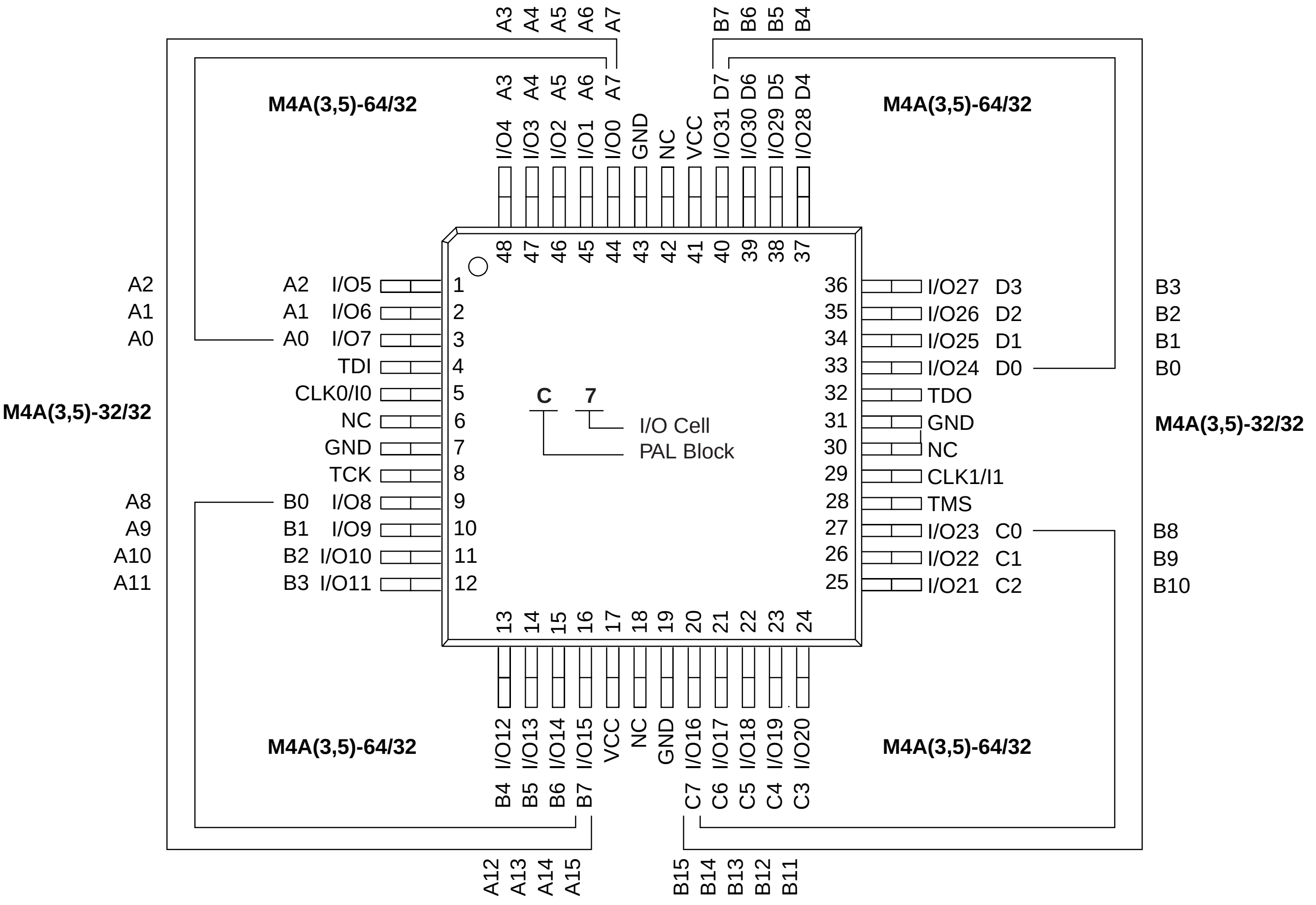
TMS = Test Mode Select

TDO = Test Data Out

48-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View

48-Pin TQFP (1.4mm Thickness)



17466G-028

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

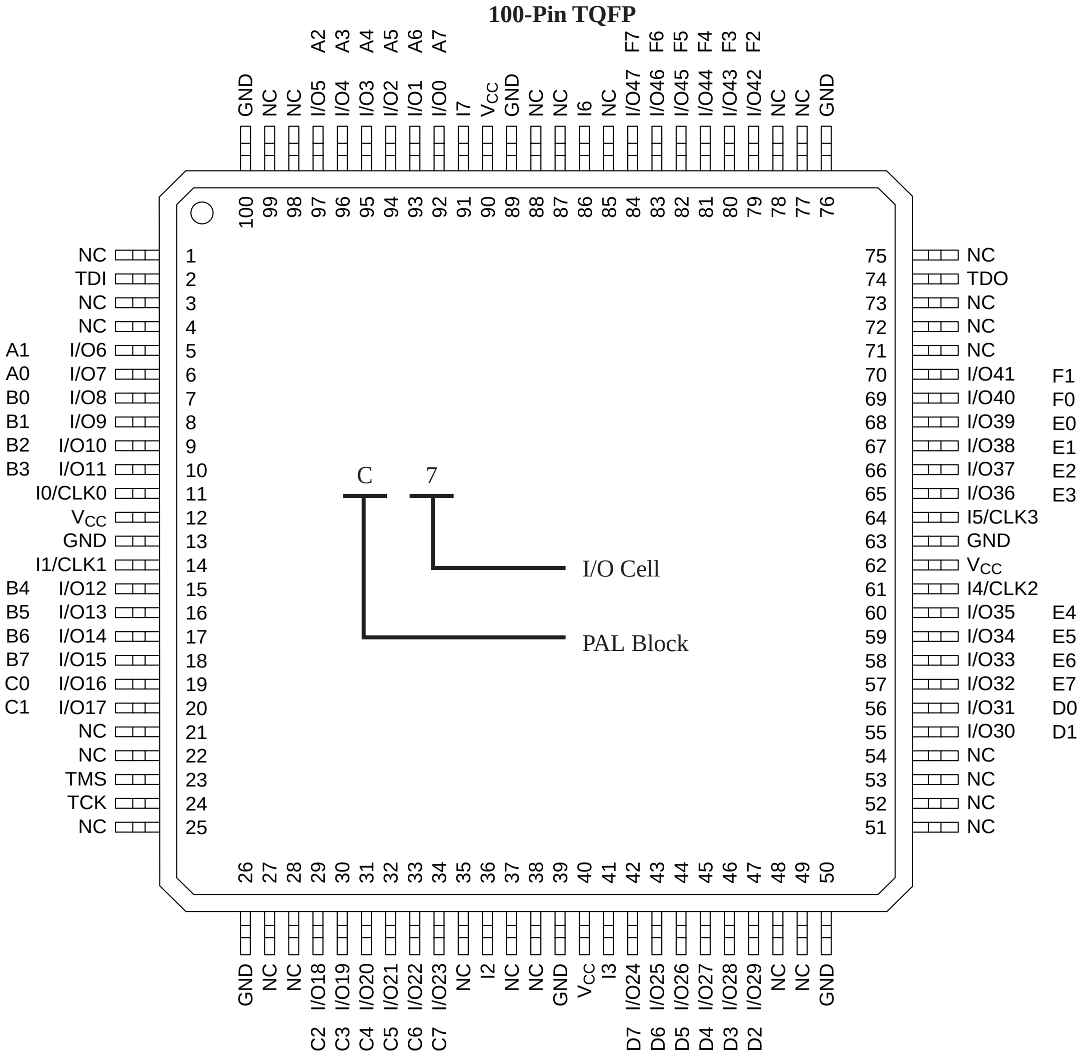
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-96/48)

Top View



17466G-029

PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

NC = No Connect

TDI = Test Data In

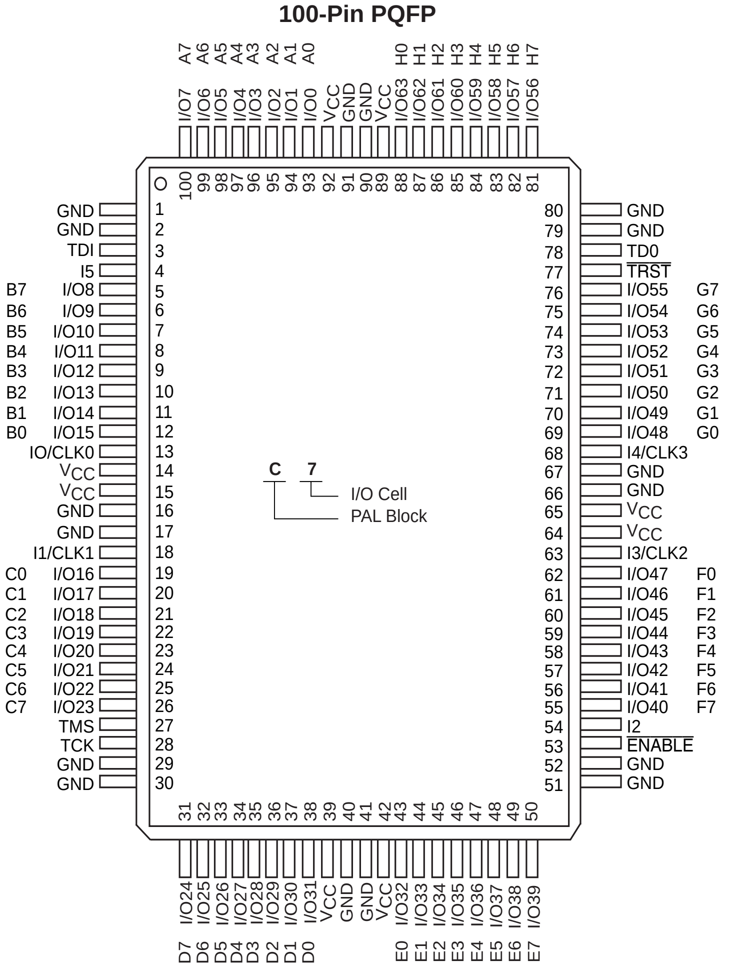
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

100-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-128/64)

Top View



17466G-031

PIN DESIGNATIONS

I/CLK = Input or Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

$\overline{\text{TRST}}$ = Test Reset

$\overline{\text{ENABLE}}$ = Program

100-BALL caBGA CONNECTION DIAGRAM (M4A3-128/64)

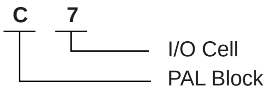
Bottom View

100-Ball caBGA

	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O63 H7	I/O60 H4	I/O57 H1	GND	GND	I/O1 A1	I/O4 A4	I/O7 A7	GND	**A**
B	$\overline{\text{TRST}}$	GND	I/O61 H5	I5	VCC	I/O0 A0	I/O6 A6	GND	TDI	I/O15 B7	**B**
C	I/O53 G5	TDO	I/O62 H6	I/O58 H2	I/O56 H0	I/O2 A2	GND	I/O14 B6	I/O13 B5	I/O12 B4	**C**
D	I/O50 G2	I/O55 G7	GND	I/O59 H3	I/O3 A3	I/O5 A5	I/O11 B3	I/O10 B2	CLK0/I0	I/O9 B1	**D**
E	CLK3/I4	I/O49 G1	I/O51 G3	I/O54 G6	VCC	I/O16 C0	I/O20 C4	I/O8 B0	VCC	GND	**E**
F	GND	VCC	I/O40 F0	I/O52 G4	I/O48 G0	VCC	I/O22 C6	I/O19 C3	I/O17 C1	CLK1/I1	**F**
G	I/O41 F1	CLK2/I3	I/O42 F2	I/O43 F3	I/O37 E5	I/O35 E3	I/O27 D3	GND	I/O23 C7	I/O18 C2	**G**
H	I/O44 F4	I/O45 F5	I/O46 F6	GND	I/O34 E2	I/O24 D0	I/O26 D2	I/O30 D6	TCK	I/O21 C5	**H**
J	I/O47 F7	$\overline{\text{ENABLE}}$	GND	I/O38 E6	I/O32 E0	VCC	I2	I/O29 D5	GND	TMS	**J**
K	GND	I/O39 E7	I/O36 E4	I/O33 E1	GND	GND	I/O25 D1	I/O28 D4	I/O31 D7	GND	**K**
	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out
$\overline{\text{TRST}}$ = Test Reset
$\overline{\text{ENABLE}}$ = Program

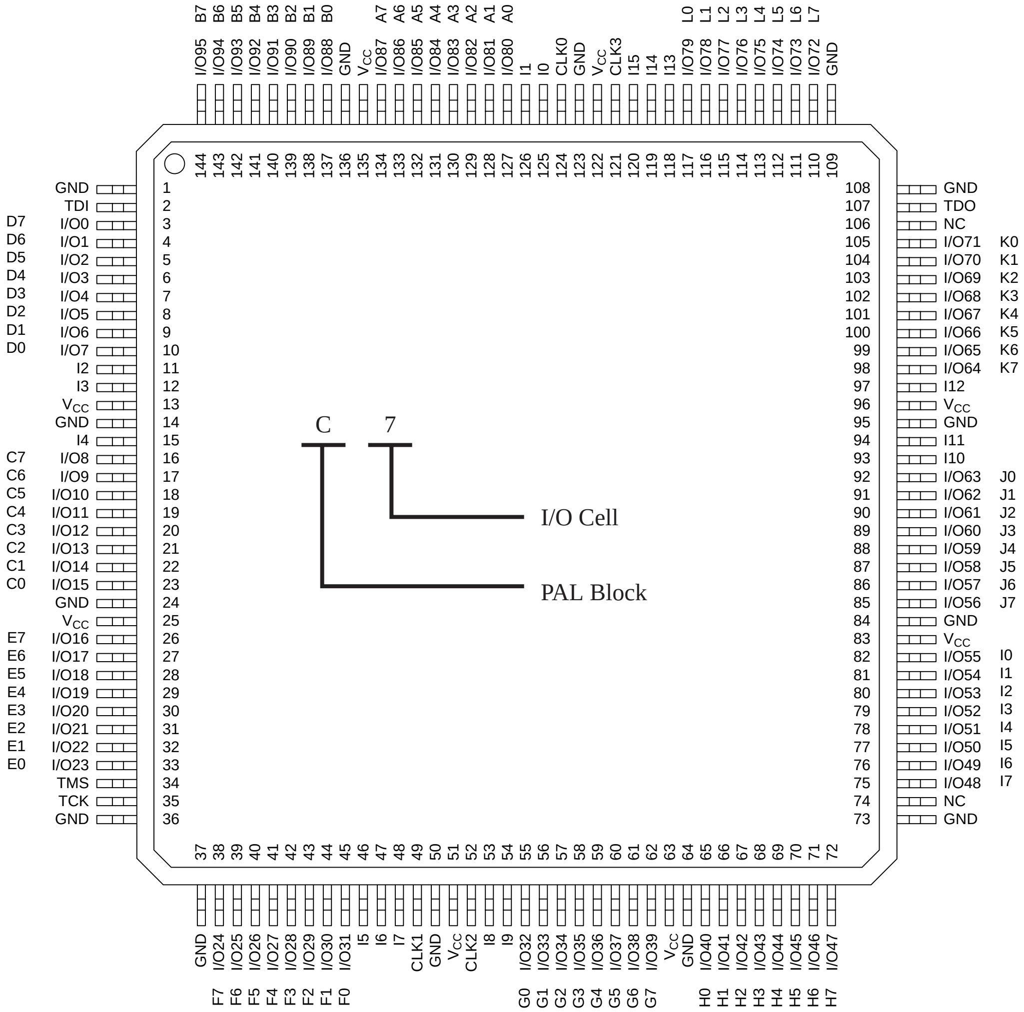


17466G-100cabga

144-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-192/96)

Top View

144-Pin TQFP



17466G-033

PIN DESIGNATIONS

CLK = Clock

GND = Ground

I = Input

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

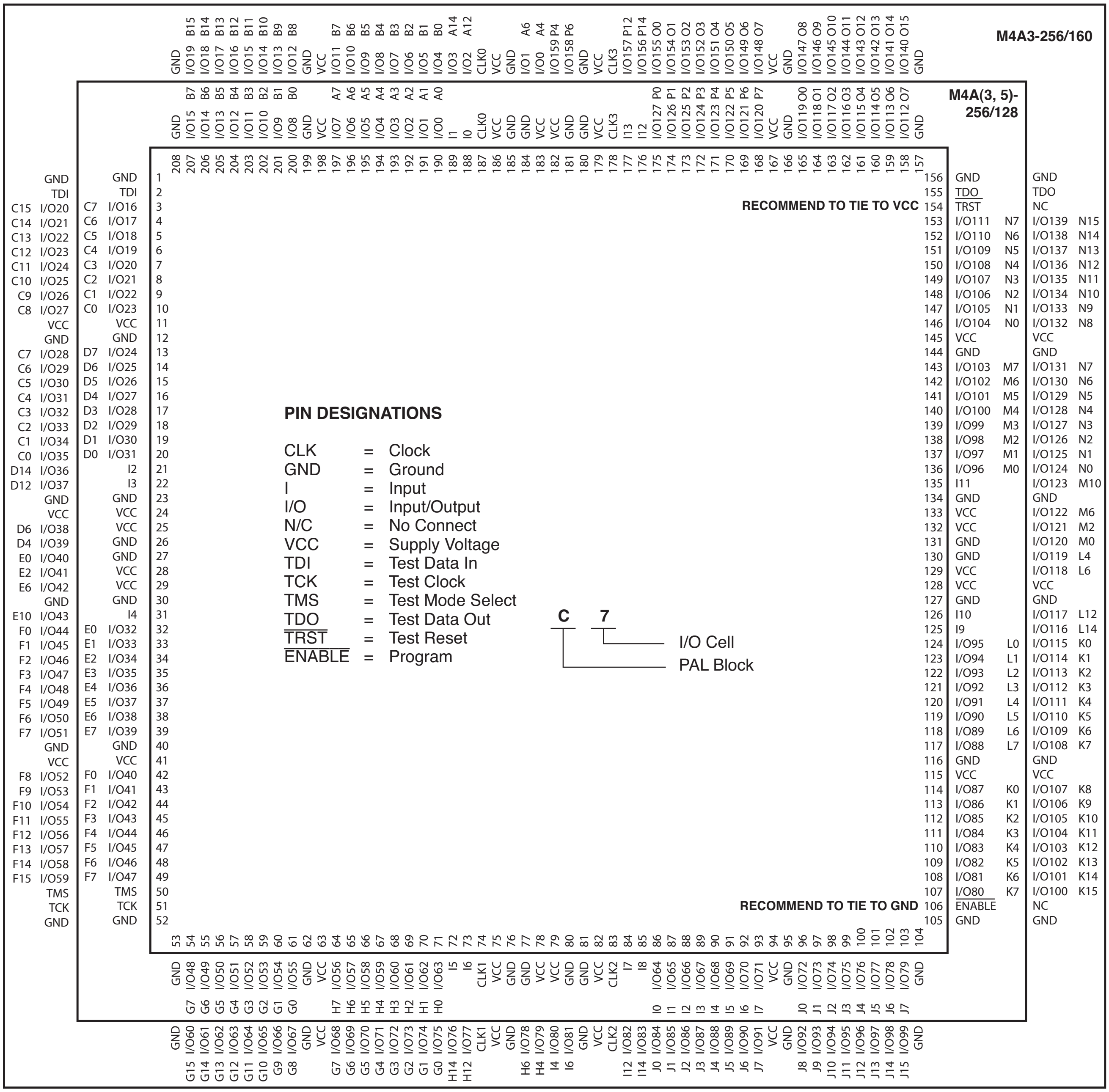
TMS = Test Mode Select

TDO = Test Data Out

208-PIN PQFP CONNECTION DIAGRAM (M4A(3,5)-256/128 AND M4A3-256/160)

Top View

208-Pin PQFP



PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out
$\overline{\text{TRST}}$ = Test Reset
$\overline{\text{ENABLE}}$ = Program

17466G-044

388-BALL fpBGA CONNECTION DIAGRAM (M4A3-512/256)

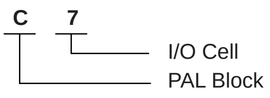
Bottom View

388-Ball fpBGA

	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O243 OX3	I/O240 OX0	I/O241 OX1	I/O236 NX4	I/O231 MX7	I/O228 MX4	I/O226 MX2	I/O255 PX7	I/O251 PX3	I/O248 PX0	I/O0 A0	I/O5 A5	I/O6 A6	I/O27 D3	I/O30 D6	I/O17 C1	I/O22 C6	I/O8 B0	I/O10 B2	N/C	GND	**A**
B	N/C	GND	I/O245 OX5	I/O242 OX2	I/O238 NX6	I/O234 NX2	I/O232 NX0	I/O229 MX5	I/O224 MX0	I/O253 PX5	I/O249 PX1	I/O2 A2	CLK0	I/O26 D2	I/O29 D5	I/O31 D7	I/O20 C4	I/O9 B1	I/O12 B4	I/O13 B5	GND	TDI	**B**
C	I/O213 KX5	TDO	GND	I/O247 OX7	I/O244 OX4	I/O239 NX7	I/O235 NX3	I/O230 MX6	I/O227 MX3	CLK3	I/O250 PX2	I/O1 A1	I/O7 A7	I/O25 D1	I/O16 C0	I/O18 C2	I/O23 C7	I/O11 B3	I/O15 B7	GND	I/O47 F7	I/O44 F4	**C**
D	I/O210 KX2	I/O212 KX4	I/O215 KX7	GND	I/O246 OX6	VCC	I/O237 NX5	I/O233 NX1	VCC	I/O254 PX6	VCC	I/O3 A3	I/O24 D0	VCC	I/O19 C3	I/O21 C5	VCC	I/O14 B6	GND	I/O46 F6	I/O43 F3	I/O41 F1	**D**
E	I/O207 JX7	I/O209 KX1	I/O211 KX3	I/O214 KX6															I/O45 F5	I/O42 F2	I/O40 F0	I/O54 G6	**E**
F	I/O203 JX3	I/O205 JX5	I/O208 KX0	VCC															VCC	I/O55 G7	I/O52 G4	I/O50 G2	**F**
G	I/O200 JX0	I/O202 JX2	I/O204 JX4	I/O206 JX6			VCC	VCC	N/C	I/O225 MX1	I/O252 PX4	I/O4 A4	I/O28 D4	N/C	VCC	VCC			I/O53 G5	I/O51 G3	I/O49 G1	I/O39 E7	**G**
H	I/O221 LX5	I/O222 LX6	I/O223 LX7	I/O201 JX1			VCC	N/C	GND	GND	GND	GND	GND	GND	N/C	VCC			I/O48 G0	I/O38 E6	I/O37 E5	I/O36 E4	**H**
J	I/O218 LX2	I/O219 LX3	I/O220 LX4	VCC			N/C	GND	GND	GND	GND	GND	GND	GND	GND	N/C			VCC	I/O35 E3	I/O34 E2	I/O32 E0	**J**
K	I/O197 IX5	I/O198 IX6	I/O199 IX7	I/O216 LX0			I/O217 LX1	GND	GND	GND	GND	GND	GND	GND	GND	I/O33 E1			I/O63 H7	I/O62 H6	I/O61 H5	I/O60 H4	**K**
L	I/O192 IX0	I/O194 IX2	I/O195 IX3	I/O196 IX4			I/O193 IX1	GND	GND	GND	GND	GND	GND	GND	GND	I/O58 H2			VCC	I/O59 H3	I/O57 H1	I/O56 H0	**L**
M	I/O184 HX0	I/O185 HX1	I/O187 HX3	VCC			I/O186 HX2	GND	GND	GND	GND	GND	GND	GND	GND	I/O69 I5			I/O67 I3	I/O65 I1	I/O66 I2	I/O64 I0	**M**
N	I/O188 HX4	I/O189 HX5	I/O191 HX7	I/O190 HX6			I/O162 EX2	GND	GND	GND	GND	GND	GND	GND	GND	I/O89 L1			I/O88 L0	I/O71 I7	I/O70 I6	I/O68 I4	**N**
P	I/O160 EX0	I/O161 EX1	I/O163 EX3	VCC			N/C	GND	GND	GND	GND	GND	GND	GND	GND	N/C			VCC	I/O92 L4	I/O91 L3	I/O90 L2	**P**
R	I/O164 EX4	I/O165 EX5	I/O166 EX6	I/O177 GX1			VCC	N/C	GND	GND	GND	GND	GND	GND	N/C	VCC			I/O74 J2	I/O95 L7	I/O94 L6	I/O93 L5	**R**
T	I/O167 EX7	I/O176 GX0	I/O179 GX3	I/O181 GX5			VCC	VCC	N/C	I/O152 DX0	I/O131 AX3	I/O122 P2	I/O98 M2	N/C	VCC	VCC			I/O78 J6	I/O76 J4	I/O73 J1	I/O72 J0	**T**
U	I/O178 GX2	I/O180 GX4	I/O183 GX7	VCC															VCC	I/O80 K0	I/O77 J5	I/O75 J3	**U**
V	I/O182 GX6	N/C	I/O169 FX1	I/O172 FX4															I/O86 K6	I/O83 K3	I/O81 K1	I/O79 J7	**V**
W	I/O168 FX0	I/O170 FX2	I/O173 FX5	GND	I/O143 BX7	VCC	I/O150 CX6	I/O145 CX1	VCC	I/O153 DX1	I/O123 P3	VCC	I/O96 M0	VCC	I/O104 N0	I/O111 N7	VCC	I/O119 O7	GND	I/O87 K7	I/O84 K4	I/O82 K2	**W**
Y	I/O171 FX3	I/O174 FX6	GND	I/O141 BX5	I/O138 BX2	I/O136 BX0	I/O147 CX3	I/O158 DX6	I/O156 DX4	CLK2	I/O132 AX4	I/O121 P1	I/O125 P5	I/O99 M3	I/O101 M5	I/O106 N2	I/O110 N6	I/O115 O3	I/O118 O6	GND	TMS	I/O85 K5	**Y**
AA	I/O175 FX7	GND	I/O142 BX6	I/O140 BX4	I/O151 CX7	I/O149 CX5	I/O144 CX0	I/O157 DX5	I/O154 DX2	I/O134 AX6	I/O130 AX2	I/O128 AX0	CLK1	I/O127 P7	I/O100 M4	I/O103 M7	I/O108 N4	I/O109 N5	I/O113 O1	I/O116 O4	GND	TCK	**AA**
AB	GND	N/C	I/O139 BX3	I/O137 BX1	I/O148 CX4	I/O146 CX2	I/O159 DX7	I/O155 DX3	I/O135 AX7	I/O133 AX5	I/O129 AX1	I/O120 P0	I/O124 P4	I/O126 P6	I/O97 M1	I/O102 M6	I/O105 N1	I/O107 N3	I/O112 O0	I/O114 O2	I/O117 O5	GND	**AB**
	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

PIN DESIGNATIONS

CLK = Clock
GND = Ground
I = Input
I/O = Input/Output
N/C = No Connect
VCC = Supply Voltage
TDI = Test Data In
TCK = Test Clock
TMS = Test Mode Select
TDO = Test Data Out



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